

What Is Claimed Is:

1. A wire bondable connector assembly comprising:
at least one lead element including a lead portion and a carrier strip portion;
5 a first coining area formed in said lead portion of said lead element;
a second coining area formed in said lead element and positioned between said lead portion and said carrier strip portion; and
a connector housing formed around said lead portion, said connector housing including said fence element covering the said first coining area such that said carrier strip portion can be separated from said lead portion without 10 affecting the stability of said lead portion.
2. A wire bondable connector assembly as described in claim 1 wherein said fence element extends to cover a portion of said second coining area.
3. A wire bondable connector assembly as described in claim 1 wherein said first coining area and said second coining area are separated by at least 0.8 mm.
4. A wire bondable connector assembly as described in claim 1 wherein said connector housing is plastic.
5. A wire bondable connector assembly as described in claim 1 wherein said fence element is formed integrally with said connector housing.
6. A wire bondable connector assembly as described in claim 1 wherein said connector housing is formed around said lead portion using injection molding.

7. A wire bondable connector assembly as described in claim 1 wherein said lead portion further include a lead surface suitable for ultrasonic wire bonding.

8. A wire bondable connector assembly as described in claim 1 for use in a high density wire bond connector.

9. A method of securing wire bondable leads in a connector housing comprising:

coining a lead element in a first coining area and a second coining area;

5 forming a connector housing over a lead portion of said lead element;

forming a fence portion over said first coining area; and

separating a carrier strip portion from said lead portion in the location of said second coining area.

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10. The method described in claim 9 further comprising the step of forming said fence portion to cover at least a portion of said second coining area.

11. The method described in claim 9 further comprising: wire bonding a wire bond to a lead surface of the lead element using ultrasonic wire bonding.

12. The method as described in claim 9 wherein said first coining area and said second coining area are at least 0.8 mm apart.

13. The method as described in claim 9 wherein said lead element is a pin.

14. The method as described in claim 9 wherein said lead element is a pad.

15. The method as described in claim 9 wherein said connector housing is molded using PBT plastic.